# 1980 Article Index

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### **Processing**

- "Processing 1981: A Progress Report," Mel H. Eklund, Jan., pg. 23.
- "Semiconductor Process Characterization by Film Thickness Analysis," D.L. Flowers and H.G. Hughes, Jan., pg. 79.
- "rianning Model Prevents Capacity Problems," W.E. Armstrong, Jan., pg. 93.
- "Photomask Making: Issues vs. Equipment," Pieter S. Burggraaf, Mar., pg. 27.
- "Multilayer Metallization Techniques for VLSI High Speed Bipolar Circuits," S.J. Rhodes, Mar., pg. 65.
- "A Practical Method of Predicting IC Yields," Michael R. Gulett, Mar., pg. 87.
- "Dry Etching Systems for Planar Processing," Timothy G. O'Neill, Apr., pg. 67.
- "Dry Etching for Pattern Transfer," H.W. Lehmann and R. Widmer, Apr., pg. 93.
- "Photolithography Equipment Decisions," Pieter S. Burggraaf, Apr., pg. 115.
- "Optical Imaging for Microfabrication," J.H. Bruning, Apr., pg. 137.
- "Process Hurdles in Electron-beam Exposure of Sub-micron Patterns," J.S. Greeneich, Apr., pg. 159.
- "Characterization of Chromium on Glass Films for Use in the Manufacture of Photomasks," D.L. Angel, P.H. Johnson and S. Calvillo, Apr., pg. 179.
- "Electron Beam and Optical Evaluation of a Dry Process Compatible Positive Photoresist," J.N. Helbert, C.C. Walker, P.A. Seese and A.J. Gonzales, Apr., pg. 199.
- "A Practical Multilayer Resist Process for 1μm Lines," Thomas Batchelder and Clifford Takemoto, Apr., pg. 213.
- "Growth of High Purity Semi-insulating Bulk GaAs for Integrated Circuit Applications," R.D. Fairman, R.T. Chen, J. Oliver and D.R. Ch'en, Apr., pg. 233.

- "The Case for Computerized Diffusion Control," Pieter S. Burggraaf, June, pg. 37.
- The Silicon Oxidation Process—Including High Pressure Oxidation," David R. Craven and James B. Stimmell, June, pg. 59.
- "High Pressure Oxidation Systems in Production," Timothy G. O'Neill, June, pg. 77.
- "Laser Processing of Semiconductors—An Update," Eugene G. Arthurs and Robert Falster, June, pg. 91.
- "Ultra-Pure Water Update," Timothy G. O'Neill, July, pg. 55.
- "Wafer Cleaning: Brush and High-Pressure Scrubbers," Pieter S. Burggraaf, July, pg. 71.
- "Wafer Cleaning: State-of-the-Art Chemical Technology," Pieter S. Burggraaf, July pg. 91.
- "Wafer Cleaning: Sonic Scrubbing," Pieter S. Burggraaf, July, pg. 97.
- "Optimizing the Cleaning Procedure for Silicon Wafers Prior to High Temperature Operations," Don Burkman, July, pg. 103.
- "Photoresist Processing Systems: The Improvements," Pieter S. Burggraaf, Aug., pg. 57.
- "Photomask Materials Review," Timothy G. O'Neill, Aug., pg. 81.
- "Pellicle Protection of IC Masks," Ron Hershel, Aug., pg. 97.
- "Anatomy of a Pure Water System," George E. Helmke, Aug., pg. 119.
- "Control of Static Electricity in Semiconductor Manufacturing," Pieter S. Burggraaf, Sept., pg. 39.
- "VLSI Metallization Problems and Trends," J.L. Vossen, Sept., pg. 91.
- "Control of Stress Gradient Reversal as a Result of Oxygen Precipitation in Silicon Wafers," E.W. Hearn, G.A. Markovits and M.V. Kulkarni, Sept., pq. 101.
- "HP's 300-MHz E-beam Lithography System Capabilities," Pieter S. Burggraaf, Sept., pg. 127.
- "Vacuum Pump Update," Ron Iscoff, Oct., pg. 39.
- "Deposition Rate Monitoring for Thin-Film Process Control," Pieter S. Burggraaf, Oct., pg. 59.
- "Glassy Carbon Coated Susceptors for Semiconductor CVD Processes," R.C. Rossi and K.K. Schuegraf, Oct., pg. 99.
- "Semiconductor Manufacturers Can Now Recycle Acid Bottles", Oct., pg. 125.

- "Ion Implantation in Wafer Fabrication," Pieter S. Burggraaf, Nov., pg. 39.
- "Wafer Annealing Systems," Ron Iscoff, Nov., pg. 69.
- "Laser Annealing," J.F. Ready, B. Thompson McClure and W.L. Larson, Nov., pg. 93.
- "Fundamentals of Silicon Epitaxy," Dr. Robert W. Atherton, Nov., pg. 117.
- "Lift-Off Techniques for Fine Line Metal Patterning," J.M. Frary and P. Seese, Dec., pg. 72.

#### Assembly

- "1981 Technology Forecast," Daniel J. Rose, Jan., pg. 35.
- "The Status of Tape Automated Bonding," Timothy G. O'Neill, Feb., pg. 33.
- "Pattern Recognition on Bonders and Probers," Pieter S. Burggraaf, Feb., pg. 53.
- "Philippine Update: Another Look at Offshore Assembly," Ron Iscoff, Feb., pg. 73.
- "VLSI Packaging Requirements and Trends," Timothy G. O'Neill, Mar., pg. 43.
- "Special Considerations in the Probing and Packaging of High Speed Digital ICs," J.A. Higgins and M.K. Kilcoyne, May, pg. 75.
- "The JEDEC Chip Carrier and LSI Standard: A Summary," Daniel I. Amey, June, pg. 103.
- "A Low Cost High Precision Envelope for a Diode Laser," P.W.M. van de Water and L.J. van Ruyven, Aug., pg. 109.
- "Getting the Maximum Return from Laser Printers in Component Identification Operations," John W. O'Neil, Sept., pg. 115.
- "The Role of Contract Assembly," Pieter Burggraaf, Dec., pg. 36.
- "Assembly Automation Trends," Ted C. Bettes, Dec., pg. 52.

#### **Testing**

- "Production LSI Testing: A 1981 Point of View," Pieter S. Burggraaf, Jan., pg. 51.
- "What is New in Memory Testing," Chris Chrones, Jan., pg. 67.
- "A Method to Analyze Eutectic Die Attach Shear Strength Data," Leopoldo Valero, Feb., pg. 85.

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- "A Practical Multilayer Resist Process for 1μm Lines," Thomas Batchelder and Clifford Takemoto, Apr., pg. 213.
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- "Control of Static Electricity in Semiconductor Manufacturing," Pieter S. Burggraaf, Sept., pg. 39.
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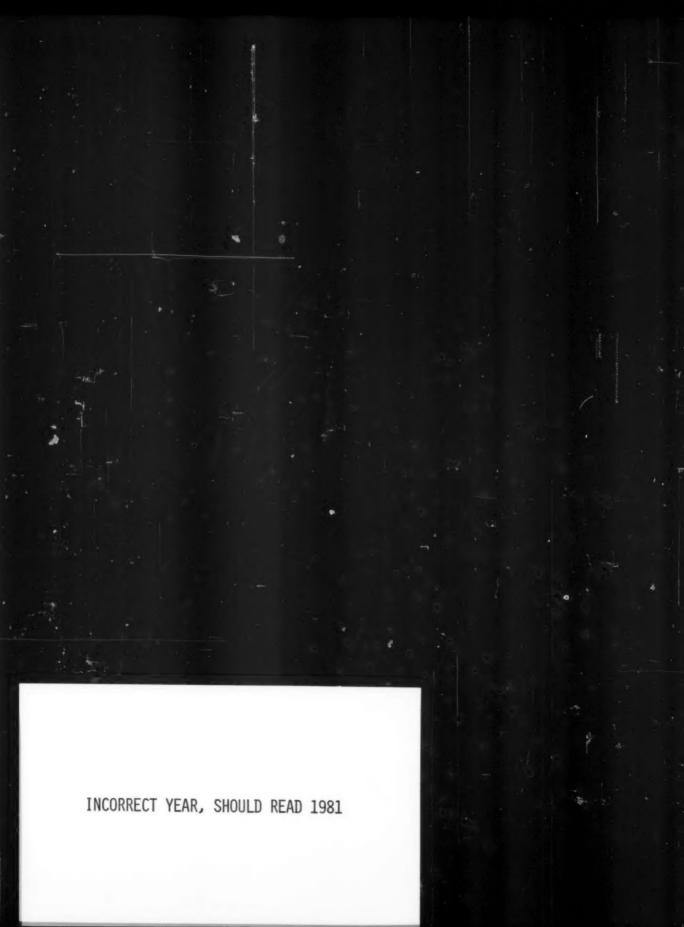
- "Ion Implantation in Wafer Fabrication," Pieter S. Burggraaf, Nov., pg. 39.
- "Wafer Annealing Systems," Ron Iscoff, Nov., pg. 69.
- "Laser Annealing," J.F. Ready, B. Thompson McClure and W.L. Larson, Nov., pg. 93.
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- "Lift-Off Techniques for Fine Line Metal Patterning," J.M. Frary and P. Seese, Dec., pg. 72.

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- "What is New in Memory Testing," Chris Chrones, Jan., pg. 67.
- "A Method to Analyze Eutectic Die Attach Shear Strength Data," Leopoldo Valero, Feb., pg. 85.





- "Evaluating Wirebond Quality," Steven W. Hinch and Donald R. Cropper, Feb., pg. 93.
- "Application of Raman Microprobe Analysis to Semiconductor Materials and Problems," C.D. Needham and J.N. Ramsey, Mar., pg. 75.
- "ECC Techniques Improve Automated Photomask Inspection," Hal Yang and Peter Eldredge, Apr., pg. 223.
- "Challenges for IC Handlers," Pieter S. Burggraaf, May, pg. 35.
- "Testing Today's LSI Chips," Chris Chrones, May, pg. 55.
- "Determining Trace Uranium in Ceramic Memory Packages Using Neutron Activation with Fission Track Counting," J.E. Riley, Jr., May, pg. 109.
- "What's New in Analog Testers," Chris Chrones, Sept., pg. 59.
- "Graphic Solution for the Back Pressurization Method of Hermetic Test," Stanley Ruthberg, Sept., pg. 73.
- "Automated Wafer Flatness Characterization System," S. Morgan, Z. Sobczak, G. Lynch and L. Reid, Oct., pg. 109.

### **Buyers Guide to Suppliers**

"Test Equipment and Services Buyers Guide," May, pg. 87.

"1981-82 Buyers Guide," Nov., pg. 133.

### Conferences and Exhibitions

- SEMICON West '81 Product Preview, Apr., pg. 259.
- 1981 International Test Conference, Sept., pg. 135.
- AVS Symposium Product Preview, Oct., pg. 86.
- ASEE Product Preview, Dec., pg. 90.
- 1981 Product Showcase, Dec., pg. 98

#### FOR MORE INFORMATION

Note the number at the end of the article. Circle this key number on the Reader Service Card opposite last page of this issue.

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### Index to Authors

Amey, Daniel I., June, pg. 103. Angel, D.L., Apr., pg. 179 Armstrong, W.E., Jan., pg. 93. Arthurs, Eugene G., June, pg. 91. Atherton, Dr. Robert W., Nov., pg. 117. Batchelder, Thomas, Apr., pg. 213. Bettes, Ted C., Dec., pg. 52 Bruning, J.H., Apr., pg. 137. Burggraaf, Pieter S., Jan., pg. 51; Feb., pg. 53; Mar., pg. 27; Apr., pg. 115; May, pg. 35; June, pg. 37; July, pgs. 71, 91, 97; Aug., pg. 57; Sept., pgs. 39, 127; Oct., pg. 59; Nov., pg. 39; Dec., pg. 36. Burkman, Don., July, pg. 103. Calvillo, S., Apr., pg. 179. Chen, R.T., Apr., pg. 233. Ch'en, D.R., Apr., pg. 233. Chrones, Chris, Jan., pg. 67; May, pg. 55; Sept., pg. 59. Craven, David R., June, pg. 59. Cropper, Donald R., Feb., pg. 93. Eklund, Mel H., Jan., pg. 23 Eldredge, Peter Apr., pg. 223. Fairman, R.D., Apr., pg. 233. Falster, Robert, June, pg. 91. Flowers, D.L., Jan., pg. 79. Frary, J.M., Dec., pg. 72. Gonzales, A.J., Apr., pg. 199 Greeneich, J.S., Apr., pg. 159 Gulett, Michael R., Mar., pg. 87. Hearn, E.W., Sept., pg. 101. Helbert, J.N., Apr., pg. 199. Helmke, George E., Aug., pg. 119. Hershel, Ron, Aug., pg. 97 Higgins, J.A., May, pg. 75. Hinch, Steven W., Feb., pg. 93. Hughes, H.G., Jan., pg. 79 Iscoff, Ron, Feb., pg. 73; Oct., pg. 39; Nov., pg. 69.

Johnson, P.H., Apr., pg. 179.
Kilcoyne, M.K., May, pg. 75.
Kulkarni, M.V., Sept., pg. 101.
Larson, W.L., Nov., pg. 93.
Lehmann, H.W., Apr., pg. 93.
Lynch, G., Oct., pg. 109.
Markovits, G.A., Sept., pg. 101.
McClure, B. Thompson, Nov., pg. 93.
Morgan, S., Oct., pg. 109.
Needham, C.D., Mar., pg. 75.
Oliver, J.R., Apr., pg. 233.
O'Neil, John W., Sept., pg. 115.
O'Neill, Timothy G., Feb., pg. 33; Mar., pg. 43; Apr., pg. 67; June, pg. 77; July, pg. 55; Aug., pg. 81.

Aug., pg. 81. Ramsey, J.N., Mar., pg. 75. Ready, J.F., Nov., pg. 93. Reid, L., Oct., pg. 109. Rhodes, S.J., Mar., pg. 65. Riley, Jr., J.E., May, pg. 109. Rose, Daniel J., Jan., pg. 35. Rossi, R.C., Oct., pg. 99. Ruthberg, Stanley, Sept., pg. 73. Schuegraf, K.K., Oct., pg. 99. Seese, P.A., Apr., pg. 199; Dec., pg. 72. Sobczak, Z., Oct., pg. 109. Stimmell, James B., June, pg. 59. Takemoto, Clifford, Apr., pg. 213. Valero, Leopoldo, Feb., pg. 85. van de Water, P.W.M., Aug., pg. 109. van Ruyven, L.J., Aug., pg. 109. Vossen, J.L., Sept., pg. 91. Walker, C.C., Apr., pg. 199. Widmer, R., Apr., pg. 93. Yang, Hal, Apr., pg. 223.



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